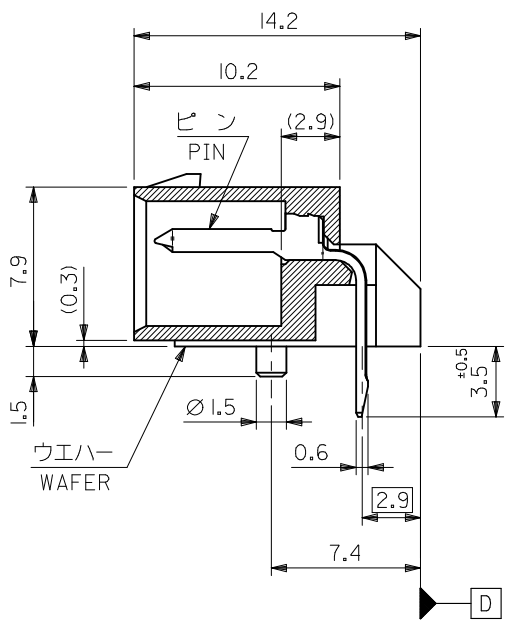
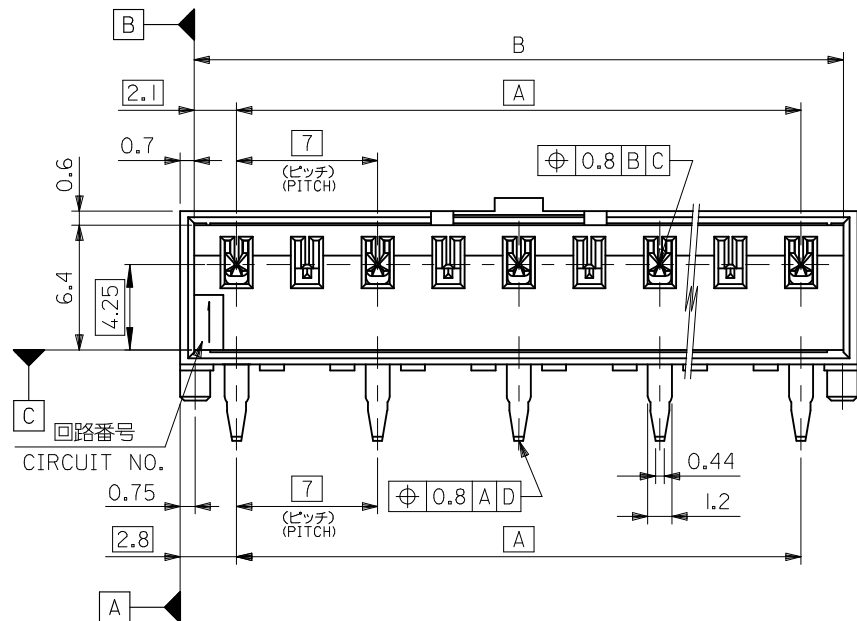


基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	54.6	53.2	49.0	53266-0829	8	
↕	40.6	39.2	35.0	-0629	6	
↕	33.6	32.2	28.0	-0529	5	
↕	26.6	25.2	21.0	-0429	4	
↕	8.7	19.6	18.2	14.0	-0329	3
6.1	12.6	11.2	7.0	53266-0229	2	
(D)	C	B	A	TRAY PACKAGE ORDER No. オーダー番号	CKT. 極数	

- 注記 NOTES
1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
 2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り)、UL94V-0
WAFER : PBTP (G.F 15%), UL94V-0
ピン : 53266-***29 [黄銅、ニッケル下地、錫メッキ (t=0.254)]
[BRASS, OVER NICKEL PLATED, TIN (t=0.254)]
 3. 本製品は53266-***20の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53266-***20.

REVISED EC NO: J2016-0718 DRWN:SSHIKONISHI 2016/01/19 CHKD:MURAKAMI 2016/01/19 APPR:TKANEKO 2016/02/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 53266-***29	
		10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE '04/05/19	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASS'Y (R/A) -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/05/19	MOLEX INCORPORATED DOCUMENT NO. SD-53266-002 SHEET NO. 1 OF 1			
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/05/19				
REV	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			